Selected Topics in Analog Integrated Circuits

Lecture 1: Weak Inversion Operation

ELC701A – Spring 2014

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- Limits of Ultra-Low-Power Analog Circuit Design
- Limits of Ultra-Low-Voltage Analog Circuit Design
- MOS transistor in Weak Inversion
 - Definition
 - Properties
 - Impact of Short-Channel Effects on Weak Inversion
- Analog Circuits in Weak Inversion

Note: Contents of this Lecture are taken from a Short Course given in ISSCC 2012

What are the fundamental lower limits to power consumption?



Average value of I_{out}

$$\overline{I_{out}} = f \cdot C \cdot V_{pp}$$

• The average power consumption P is then given by

$$P = V_{DD} \cdot f \cdot C \cdot V_{pp} = \frac{V_{DD}}{V_{pp}} \cdot f \cdot C \cdot V_{pp}^2$$

The noise current power spectral density (PSD) is given by

$$S_{Ni} = 4kT \cdot \gamma \cdot G_m$$

The total mean square noise voltage across capacitor C is given by

$$V_N^2 = \frac{\gamma \cdot kT}{C}$$

- Where γ is the noise excess factor which will be assumed to be unity
- The signal-to-noise ratio SNR is then given by

$$SNR = \frac{V_{pp}^2/8}{kT/C} \rightarrow V_{pp}^2 = \frac{8kT}{C} \cdot SNR$$

The power consumption can then be written as

$$P = 8 \cdot \frac{V_{DD}}{V_{pp}} \cdot kT \cdot f \cdot SNR$$

 Power consumption is minimized by maximizing the peak-to-peak signal with railto-rail operation V_{pp}=V_{DD}

$$P_{\min} = 8 \cdot kT \cdot f \cdot SNR$$

- P is proportional to frequency which actually corresponds to the bandwidth B for low-pass filters
- A factor of merit (actually demerit, the smaller the better) can be defined as

$$K = \frac{P}{kT \cdot B \cdot SNR} = 8 \cdot \frac{V_{DD}}{V_{pp}}$$

K is minimum for V_{pp}=V_{DD} (rail-to-rail linear operation)

$$K_{\min} = K \big|_{V_{pp} = V_{DD}} = 8$$

- The minimum power consumption P_{min} is proportional to frequency (bandwidth)
- It corresponds to an absolute minimum for processing a signal with an analog circuit



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- K_{min} constitute an absolute minimum not accounting for many non-idealities
- In practical analog circuits there are many non-idealities that can seriously degrade (increase) the K factor far beyond K_{min}
 - Current inefficiency (non-ideal class B operation)
 - Linearity requirement
 - Additional bias circuits
 - Limited matching
 - Additional noise contributions (from flicker noise and from other devices)
 - Parasitic capacitances
 - Charge injection



 K factor of a generic transconductor is given by

$$K = \frac{P}{kT \cdot B \cdot SNR} \ge 4\gamma_{eq} \frac{V_{DD} \cdot I_{DD}}{V_{in-rms}^2 \cdot G_m}$$

 Can be minimized by maximizing V_{in}/V_{DD} (rail-to-rail operation) and G_m/I_{DD} (bias in weak inversion)



 Example of a simple NMOS transconductor biased in SI for better linearity

$$K > 8\gamma n \cdot \left(\frac{V_{DSsat}}{V_{in}\text{-}rms}\right)^2$$

 Can be minimized by reducing V_{DSsat} and hence the supply voltage V_{DD} However, decreasing V_{DSsat} increases the total harmonic distortion THD due to the square-law characteristic according to

$$THD = \frac{V_{in}}{4nV_{DSsat}} = \frac{\sqrt{2} \cdot V_{in-rms}}{4nV_{DSsat}} \rightarrow \left(\frac{V_{DSsat}}{V_{in-rms}}\right)^2 = \frac{1}{8n^2 \cdot THD^2}$$

K can then be expressed directly in terms of the THD as

$$K > \frac{\gamma}{THD^2} = \frac{2}{3 \cdot THD^2}$$

Having THD < 1% requires K > 6700 instead of 8 (factor 840 higher!)

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- Two main motivations for low-voltage:
 - 1. Reduce the **dynamic power consumption** of digital circuits according to

$$P_{dyn} = f \cdot C \cdot V_{DD}^2$$

- 2. Maintaining limited electric field in the device and avoid strong short-channel effects due to process down-scaling
- But definitely NOT to reduce the power consumption of analog circuits
- Low-voltage usually results in higher power consumption for analog circuits
- Low-voltage is often imposed the full system integration (system-on-a-chip or SoC approach) including analog and RF in deep-submicron technologies
- Low-voltage can also be imposed by energy-scavenging sources producing only small supply voltages



 Assuming uncompressible and equal saturation voltages for NMOS and PMOS, the minimum supply voltage for a given signal voltage swing is given by

$$V_{DD} = V_{pp} + 2V_{DSsat} \rightarrow V_{pp} = V_{DD} - 2V_{DSsat}$$

The power consumption is now given by

$$P = K_{\min} \cdot \frac{V_{DD}}{V_{DD} - 2V_{DSsat}} \cdot kT \cdot B \cdot SNR \quad \text{or} \quad \frac{K}{K_{\min}} = \frac{V_{DD}}{V_{DD} - 2V_{DSsat}}$$

Most fundamental

- Voltage swing given by V_{pp} ≤ V_{DD} − 2·V_{DSsat}
- If $V_{DSsat} = V_{DD}/2$ (or $V_{pp} = 0$) then K >>> 1
- If voltage is split half between bias and signal: V_{DSsat} = V_{DD}/4 (or V_{pp} = V_{DD}/2) then K acceptable
- V_{pp} and V_{DSsat} must therefore be reduced proportionally with V_{DD}, consequently, inversion coefficient has to be reduced and operating point is progressively moving towards moderate and weak inversion
- Other consequences:
 - V_{DD} approaching $V_T \rightarrow$ poor switch conductance (eventually conductance gap)
 - If V_T is lowered \rightarrow open switches start to leak
 - ▶ V_{DD} below V_{G0} → requires special band-gap voltage reference circuits
 - Transistor stacks no more possible ightarrow requires special LV circuit techniques

Minimum Supply in Weak Inversion for Different V_T



- Supply voltage below 1V pushes bias point towards moderate/weak inversion
- For achieving V_{DD}=0.5V, threshold voltage should be smaller than 0.3 V and bias point has to be in weak inversion (IC < 0.1)

Bulk MOSFET Models

- BSIM3
 - Threshold Voltage based MOSFET Model
 - First CMC standard Model
 - BSIM4
 - Threshold Voltage based MOSFET Model with enhanced physics features (mobility, BTBT, gate leakage.....)



- BSIM6
- Charge based Symmetric MOSFET Model
 - Charge based core
 - BSIM4 physics models and parameters
- Under standardization review in CMC

- BSIM6 Model description (EKV)
- Why use Charge-based Models?
- Background on Charge Based Symmetric Model
- Charge, Current and Voltage Expressions in more details
- All transconductances expressions
- Special Cases
- Important Derivations

[REF1] C. C. Enz and E. A. Vittoz, *Charge-Based MOS Transistor Modeling - The EKV Model for Low-Power and RF IC Design*, John Wiley, 2006.

[REF2] E. A. Vittoz and C. C. Enz, "EKV Model of the MOS Transistor," in *Sub-Threshold Design for Ultra Low-Power Systems*, Springer, 2006.

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$$I_D = \mu \cdot W \cdot (-Q_i) \cdot \frac{dV}{dx} \implies I_D = \beta \cdot \int_{V_S}^{V_D} \frac{-Q_i}{C_{ox}} \cdot dV \quad \text{with} \quad \beta = \mu \cdot C_{ox} \cdot \frac{W}{L}$$



- Q_i is the inversion mobile charge density (electrons for n-channel)
- V is the channel voltage (electrons quasi-Fermi potential), equal to V_S at the source and V_D at the drain
- V_P is the **pinch-off voltage** given by

$$V_P \cong \frac{V_G - V_{T0}}{n}$$

- V_{T0} is the threshold voltage (at V=0)
- n is the slope factor
- µ is the electron mobility (at low field)

- $I_D = I_F I_R$
- Normalized drain current (Inversion Coefficient IC):
 - $i_d = i_f i_r = (q_s^2 + q_s) (q_d^2 + q_d)$
 - q_s: Normalized charge density in the channel near the source
 - q_d : Normalized charge density in the channel near the drain

Modes of Operation (i_f versus i_r)



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$$i_{f(r)} = \frac{I_{F(R)}}{I_{spec}} = \ln^2 \left(1 + e^{\frac{V_P - V_{S(D)}}{2U_T}} \right) \cong \ln^2 \left(1 + e^{\frac{V_G - V_{T0} - n \cdot V_{S(D)}}{2n \cdot U_T}} \right)$$

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- Strong inversion spans over wide range of voltage, but...
- Moderate and weak inversion span over more than 6 decades of current, whereas strong inversion is limited to less than 2 decades

Drain current in weak inversion

$$I_D = I_F - I_R = I_{spec} \cdot \left(i_f - i_r\right) \quad \text{with} \quad I_{F(R)} = I_{spec} \cdot e^{\frac{V_P - V_{S(D)}}{U_T}}$$

where I_F (i_f) and I_R (i_r) are the **forward** and **reverse** (normalized) currents, respectively and I_{spec} is the **specific current** defined by

$$I_{spec} = 2n \cdot \beta \cdot U_T^2 = I_{spec} \cdot \frac{W}{L}$$

with
$$\beta = \mu \cdot C_{ox} \cdot \frac{W}{L}$$
 and $I_{spec} = 2n \cdot \mu \cdot C_{ox} \cdot U_T^2$

V_P is the pinch-off voltage given by

$$V_P = \frac{V_G - V_{T0}}{n}$$

The drain current can then be written as

$$I_D = I_{spec} \cdot e^{\frac{V_G - V_{T0}}{n \cdot U_T}} \cdot \left[e^{-\frac{V_S}{U_T}} - e^{-\frac{V_D}{U_T}} \right]$$



The drain current can also be written as

$$I_D = I_F \cdot \left(1 - \frac{I_R}{I_F}\right) = I_F \cdot \left(1 - e^{-\frac{V_{DS}}{U_T}}\right)$$

Saturation is reached for V_{DS} >> U_T

$$I_D = I_F = I_{spec} \cdot e^{\frac{V_P - V_S}{U_T}} = I_{spec} \cdot e^{\frac{V_G - V_T - n \cdot V_S}{nU_T}} = I_{D0} \cdot e^{\frac{V_G - n \cdot V_S}{nU_T}}$$

where I_{D0} is the **leakage current** (current flowing in saturation for $V_G = V_S = 0$)

$$I_{D0} = I_{spec} \cdot e^{\frac{V_{T0}}{n \cdot U_T}}$$

Leakage current highly sensitive to threshold voltage

The saturation voltage V_P-V_S can be expressed in terms of the V_{GS} voltage as

$$V_P - V_S \cong \frac{V_G - V_{T0} - n \cdot V_S}{n} = \frac{V_{GS} - V_T}{n}$$

where V_T is the threshold voltage for $V_S > 0$

$$V_T = V_{T0} + (n-1) \cdot V_S$$

 The drain current in forward saturation (forward current) can then be written in terms of the V_{GS} voltage as

$$i_d = \frac{I_D}{I_{spec}} \cong i_f \cong \ln^2 \left(1 + e^{\frac{V_{GS} - V_T}{2n \cdot U_T}} \right)$$

Which in weak inversion and forward saturation reduces to

$$i_d = \frac{I_D}{I_{spec}} \cong \cdot e^{\frac{V_{GS} - V_T}{nU_T}}$$

- Overdrive voltage V_{GS}-V_T not convenient for weak inversion
- Replaced by the inversion coefficient IC characterizing the global level of inversion of the transistor and formerly defined as

$$IC = \max(i_f, i_r)$$

In saturation i_f >> i_r and therefore

 $IC = i_f = \frac{I_D}{I_{spec}} = \frac{I_D}{I_{spec}} \cdot \frac{W}{L} \quad \text{(saturation)} \quad \text{with} \quad I_{spec} = 2n \cdot \mu \cdot C_{ox} \cdot U_T^2$

- The different regions of operation in saturation can then be defined as
 - IC < 0.1: weak inversion (WI)
 - 0.1 < IC < 10: moderate inversion (MI)
 - 10 < IC: strong inversion (SI)

 The inversion coefficient IC (in saturation) can be expressed in terms of the overdrive voltage V_{GS}-V_T and reversely



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- Weak inversion provides the minimum saturation voltage ($V_{DSsat} \cong 4$ to 5 U_T)
- This is the main reason why weak inversion is intrinsically associated with lowvoltage circuit design
- Unlike strong inversion, this saturation voltage is independent of the threshold voltage

The current efficiency (in saturation) is maximum in weak inversion

current efficiency =
$$\frac{G_{ms} \cdot U_T}{I_D} = \frac{G_m \cdot n \cdot U_T}{I_D} = \frac{1}{q_s + 1} = \frac{2}{\sqrt{4IC + 1} + 1} = \begin{cases} 1 & WI \\ \frac{1}{\sqrt{IC}} & SI \end{cases}$$



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- Above plot shows the THD in % versus the inversion factor for different sinewave input amplitudes
- Linearity is strongly degraded compared to SI due to the exponential I-V characteristic

Assuming ΔV_{T0} and Δβ are uncorrelated and Δn is negligible, the standard deviation of the relative drain current mismatch of two transistors biased in saturation with the same gate and source voltages (current mirror) is given by

$$\sigma_{\frac{\Delta I_D}{I_D}} = \sqrt{\sigma_{\frac{\Delta\beta}{\beta}}^2 + \left(\frac{G_m}{I_D}\right)^2} \cdot \sigma_{\Delta V_{T0}}^2$$

with $\sigma_{\frac{\Delta\beta}{\beta}} = \frac{A_{\beta}}{\sqrt{W \cdot L}}$ and $\sigma_{\Delta V_{T0}} = \frac{A_{VT}}{\sqrt{W \cdot L}}$ with $A_{VT} \propto t_{ox} \cdot \sqrt[4]{N_b} \propto \frac{\sqrt[4]{\kappa}}{\kappa} = \frac{1}{\kappa^{\frac{3}{4}}}$

 The standard deviation of the gate voltage mismatch of two transistors biased in saturation with identical drain current (diff pair) is given by

$$\sigma_{\Delta V_{G}} = \sqrt{\sigma_{\Delta V_{T0}}^{2} + \left(\frac{I_{D}}{G_{m}}\right)^{2} \cdot \sigma_{\frac{\Delta \beta}{\beta}}^{2}}$$







- Current matching bad in weak inversion
- Gate voltage matching best in weak inversion
- Nonzero V_S degrades matching, (particularly current matching in WI) due to correlation between ΔV_{T0} and Δn (both depend on doping variation ΔN_b)

$$\sigma_{\Delta V_T}\Big|_{V_S > 0} = \sigma_{\Delta V_{T0}} \cdot \left(1 + \frac{V_S}{2\Psi_0}\right)$$

The transit frequency in WI and saturation is given by

$$\omega_t = \frac{G_m}{C_G} = \frac{G_m}{C_{Gi} + C_{Ge}} \cong \omega_{t0} \cdot IC$$

where C_G is the **total gate capacitance** made of the intrinsic C_{Gi} and extrinsic C_{Ge} gate capacitances respectively, and ω_{t0} is defined as the ω_t (in WI) for IC=1

- **Proportional to inversion coefficient** (instead of \sqrt{IC} in SI)
- Takes full advantage of 1/L² scaling since there is no high field effects such as velocity saturation and mobility reduction due to the vertical field
- Extrinsic capacitances (overlap and fringing capacitances) strongly reduce the ft (typically a factor 3 compared to intrinsic ft)
- For typical 65 nm process $f_{t0} \cong$ 300 GHz for n-channel MOST (standard V_T)

Pros

- Exponential I-V characteristic similar to bipolar
- Minimum drain saturation voltage
- Minimum gate voltage
- Minimum gate capacitance
- Maximum current efficiency G_m/I_D
 - Max. intrinsic voltage gain
 - Min. input noise PSD for given I_D
 - Max. bandwidth for given kT/C and I_D
 - Min. input offset voltage

Cons

- Higher distortion
- Low speed
- Low f_t compared to strong inversion, but increases with scaling (weak inversion is more and more interesting for deep-submicron technologies)
 - Max. output noise current for a given I_D
 - Max. current mismatch (poor current accuracy)

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A high longitudinal electric field E_x causes the carrier velocity v_{drift} to saturate





- Velocity saturation has a strong impact on the drain current in strong inversion
- The current becomes proportionnal to V_G-V_{T0}
- Hence the gate and source transconductances become independent of the current (and independent of the length)



• Scaling of ω_t is affected by short-channel effects such as velocity saturation

$$\begin{array}{c} G_{msat} \cong W \cdot C_{ox} \cdot v_{sat} \\ C_G \propto W \cdot L_f \cdot C_{ox} \end{array} \end{array} \rightarrow \mathcal{O}_t = \frac{G_{msat}}{C_G} \propto \frac{v_{sat}}{L_f}$$

Scales only as 1/L_f instead of 1/L_f² when velocity saturation is present

